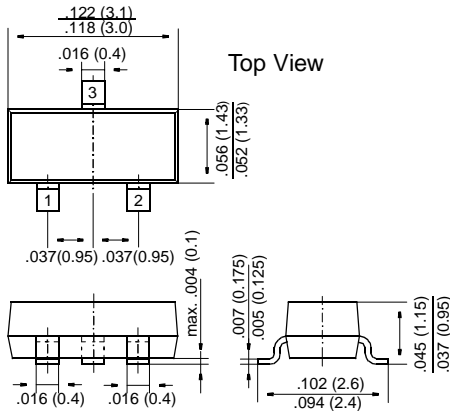


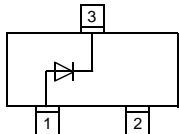
BAT54 THRU BAT54S

Schottky Diodes

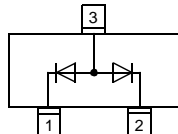
SOT-23



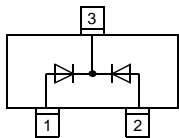
Dimensions in inches and (millimeters)



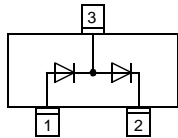
BAT54
Marking: L4



BAT54A
Marking: L42



BAT54C
Marking: L43



BAT54S
Marking: L44

FEATURES

- ◆ These diodes feature very low turn-on voltage and fast switching.
- ◆ These devices are protected by a PN junction guard ring against excessive voltage, such as electrostatic discharges.



MECHANICAL DATA

Case: SOT-23 Plastic Package

Weight: approx. 0.008 g

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS FOR ONE DIODE

Ratings at 25 °C ambient temperature unless otherwise specified

| | Symbol | Value | Unit |
|---|-----------|-------------------|------|
| Repetitive Peak Reverse Voltage | V_{RRM} | 30 | V |
| Forward Continuous Current at $T_{amb} = 25\text{ °C}$ | I_F | 200 ¹⁾ | mA |
| Repetitive Peak Forward Current at $T_{amb} = 25\text{ °C}$ | I_{FRM} | 300 ¹⁾ | mA |
| Surge Forward Current at $t_p < 1\text{ s}$, $T_{amb} = 25\text{ °C}$ | I_{FSM} | 600 ¹⁾ | mA |
| Junction Temperature | T_j | 150 | °C |
| Storage Temperature Range | T_S | -65 to +150 | °C |

¹⁾ Device on fiberglass substrate, see layout.

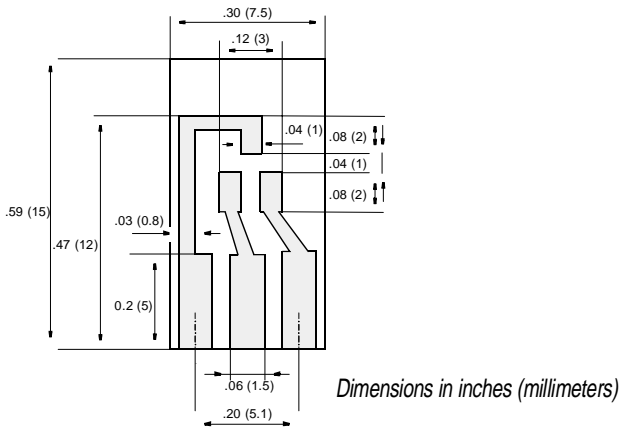
BAT54 THRU BAT54S

ELECTRICAL CHARACTERISTICS

Ratings for one diode at 25 °C ambient temperature unless otherwise specified

| | Symbol | Min. | Typ. | Max. | Unit |
|---|-------------|------|------|-------------------|---------|
| Reverse Breakdown Voltage tested with 100 μ A Pulses | $V_{(BR)R}$ | 30 | – | – | V |
| Forward Voltage Pulse Test $t_p < 300 \mu s$, $\delta < 2\%$ at $I_F = 0.1 \text{ mA}$ | V_F | – | – | 240 | mV |
| at $I_F = 1 \text{ mA}$ | V_F | – | – | 320 | mV |
| at $I_F = 10 \text{ mA}$ | V_F | – | – | 400 | mV |
| at $I_F = 30 \text{ mA}$ | V_F | – | – | 500 | mV |
| at $I_F = 100 \text{ mA}$ | V_F | – | – | 1000 | mV |
| Leakage Current Pulse Test $t_p < 300 \mu s$, $\delta < 2\%$ at $V_R = 25 \text{ V}$ | I_R | – | – | 2 | μ A |
| Capacitance at $V_F = 1 \text{ V}$, $f = 1 \text{ MHz}$ | C_{tot} | – | – | 10 | pF |
| Reverse Recovery Time from $I_F = 10 \text{ mA}$ through $I_R = 10 \text{ mA}$ to $I_R = 1 \text{ mA}$, $R_L = 100 \Omega$ | t_{rr} | – | – | 5 | ns |
| Thermal Resistance Junction to Ambient Air | R_{thJA} | – | – | 430 ¹⁾ | K/W |

¹⁾ Device on fiberglass substrate, see layout



Layout for R_{thJA} test

Thickness: Fiberglass 0.059 in (1.5 mm)

Copper leads 0.012 in (0.3 mm)